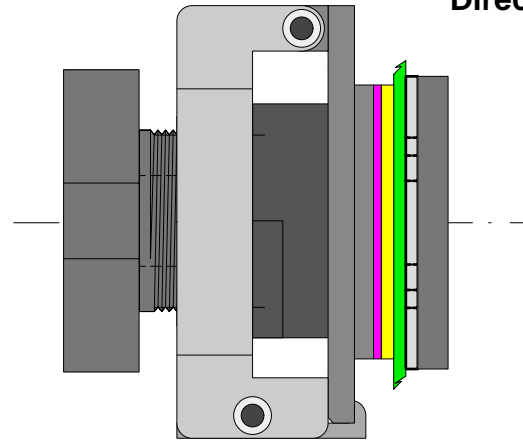
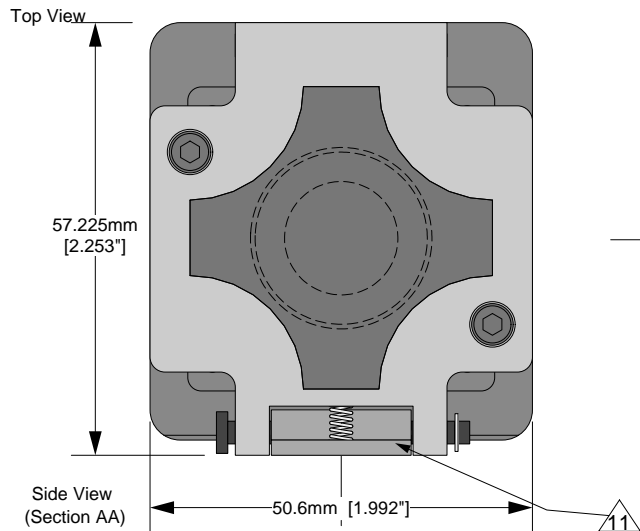


Top View

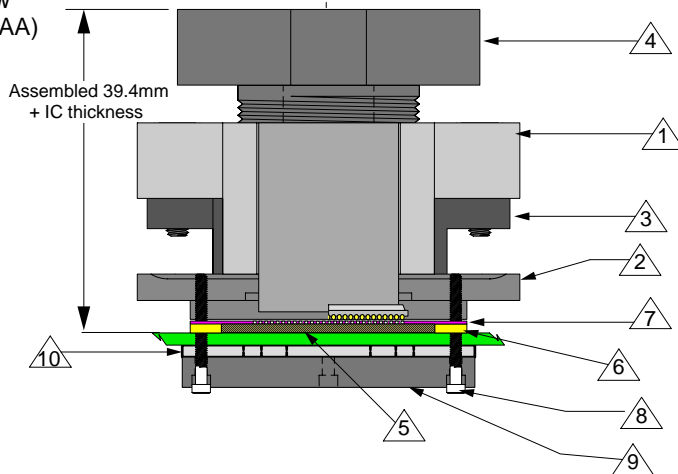


GHz CLAMSHELL BGA Socket - Direct mount, solderless

Features

- Directly mounts to target PCB (needs tooling holes) with hardware
- Minimum real estate required
- Compression plate distributes forces evenly
- Clamshell lid

Side View
(Section AA)



- 1 Clam Shell Lid: Black anodized Aluminum. Height = 20 mm.
- 2 Socket base: Black anodized Aluminum. Thickness = 6mm.
- 3 Compression Plate: Black anodized Aluminum. Thickness = 12mm.
- 4 Compression screw: Clear anodized Aluminum. Thickness = 27mm, Fluted Knob.
- 5 Elastomer: 40 micron dia gold plated brass filaments arranged symmetrically in a silicone rubber (63.5 degree angle). Thickness = 0.75mm.
- 6 Elastomer Guide: Cirlex or equivalent. Thickness = 0.75mm.
- 7 Ball Guide: Kapton polyimide.
- 8 Socket base screw: Socket head cap, alloy steel with black oxide finish, 0-80 fine thread, 9.525mm long.
- 9 Backing Plate: Black anodized Aluminum. Thickness = 4mm.
- 10 Insulation Plate: FR4/G10, Thickness = 1.59mm.
- 11 Latch: Black anodized Aluminum.

CG-BGA-4001 Drawing

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11351 Rupp Drive, Suite 400, Burnsville, MN 55337
Tele: (952) 229-8200
www.ironwoodelectronics.com

Status: Released

Scale: -

Rev: A

Drawing: J. Glab

Date: 7/30/07

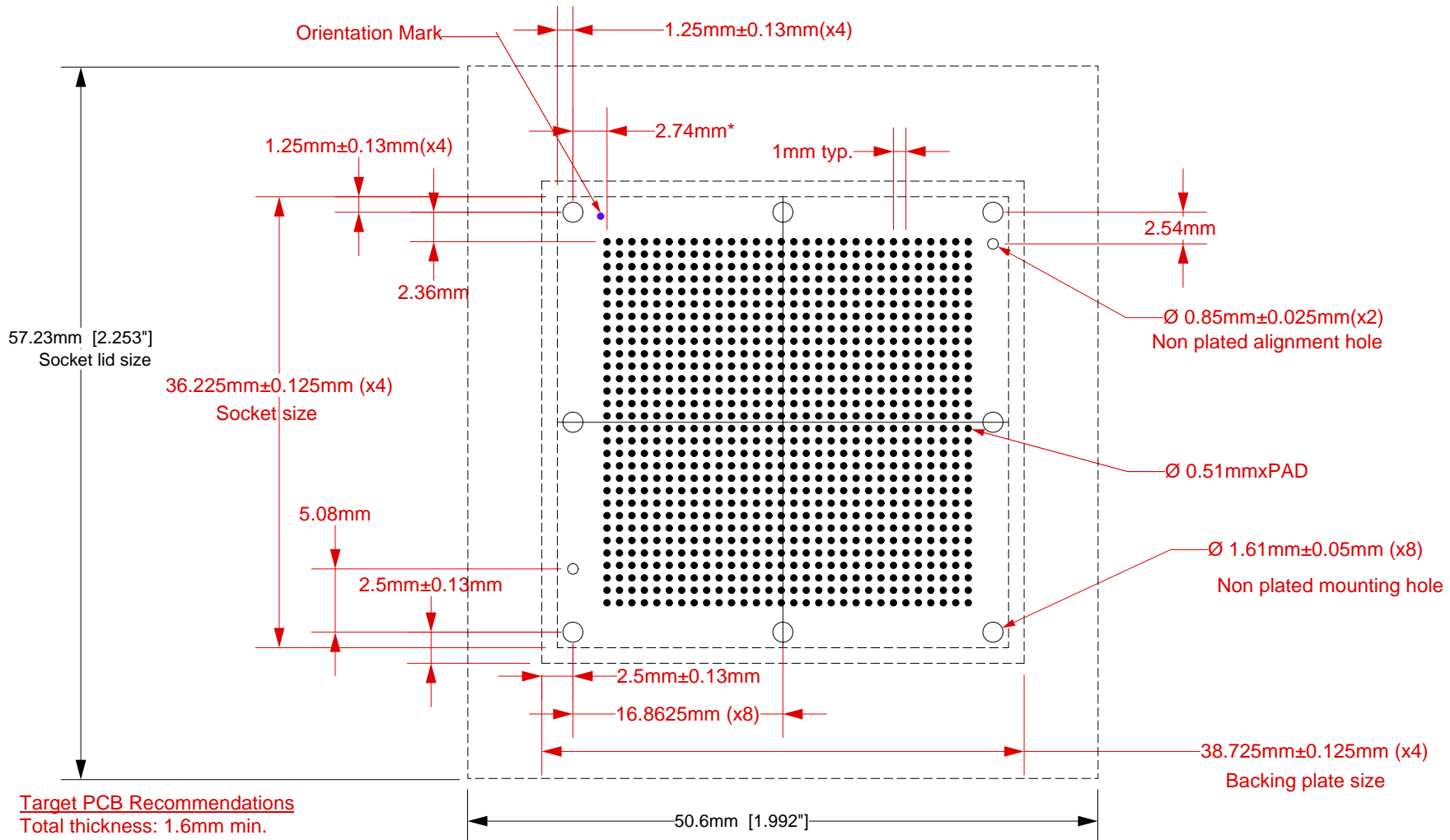
File: CG-BGA-4001 Dwg.mcd

Modified:

All tolerances: ± 0.125 mm (unless stated otherwise). Materials and specifications are subject to change without notice.

Recommended PCB Layout
Top View

***Note: BGA pattern is not symmetrical with respect to the mounting holes.**




Target PCB Recommendations

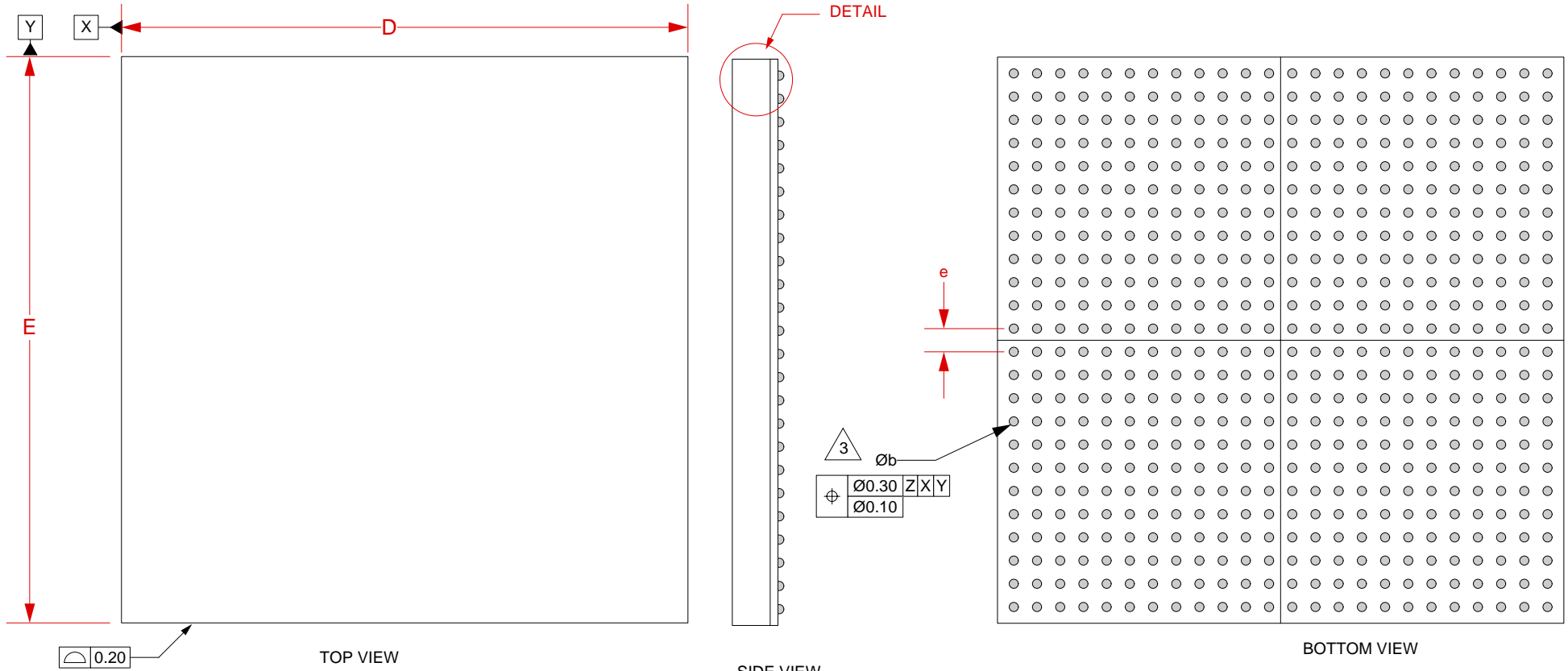
Total thickness: 1.6mm min.
Plating: Gold or Solder finish
PCB Pad height: Same or higher than solder mask

NOTE: Steel backing plate may be required based on end user's application

Recommended PCB Layout Tolerances: $\pm 0.025\text{mm}$ [± 0.001 "] unless stated otherwise.

CG-BGA-4001 Drawing		Status: Released	Scale: 2:1	Rev: A
 <p>© 2007 IRONWOOD ELECTRONICS, INC. 11351 Rupp Drive, Suite 400, Burnsville, MN 55337 Tele: (952) 229-8200 www.ironwoodelectronics.com</p>	Drawing: J. Glab		Date: 7/30/07	
	File: CG-BGA-4001 Dwg.mcd		Modified:	

Compatible BGA Spec

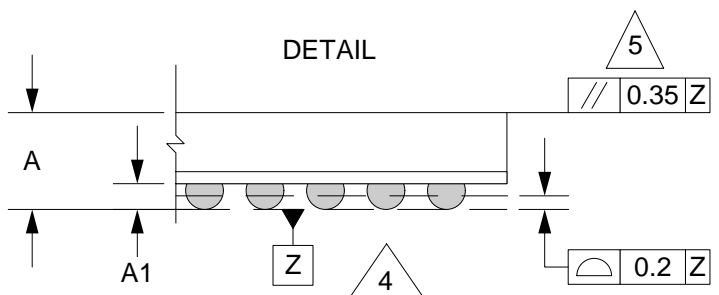


0.20

TOP VIEW

SIDE VIEW

BOTTOM VIEW



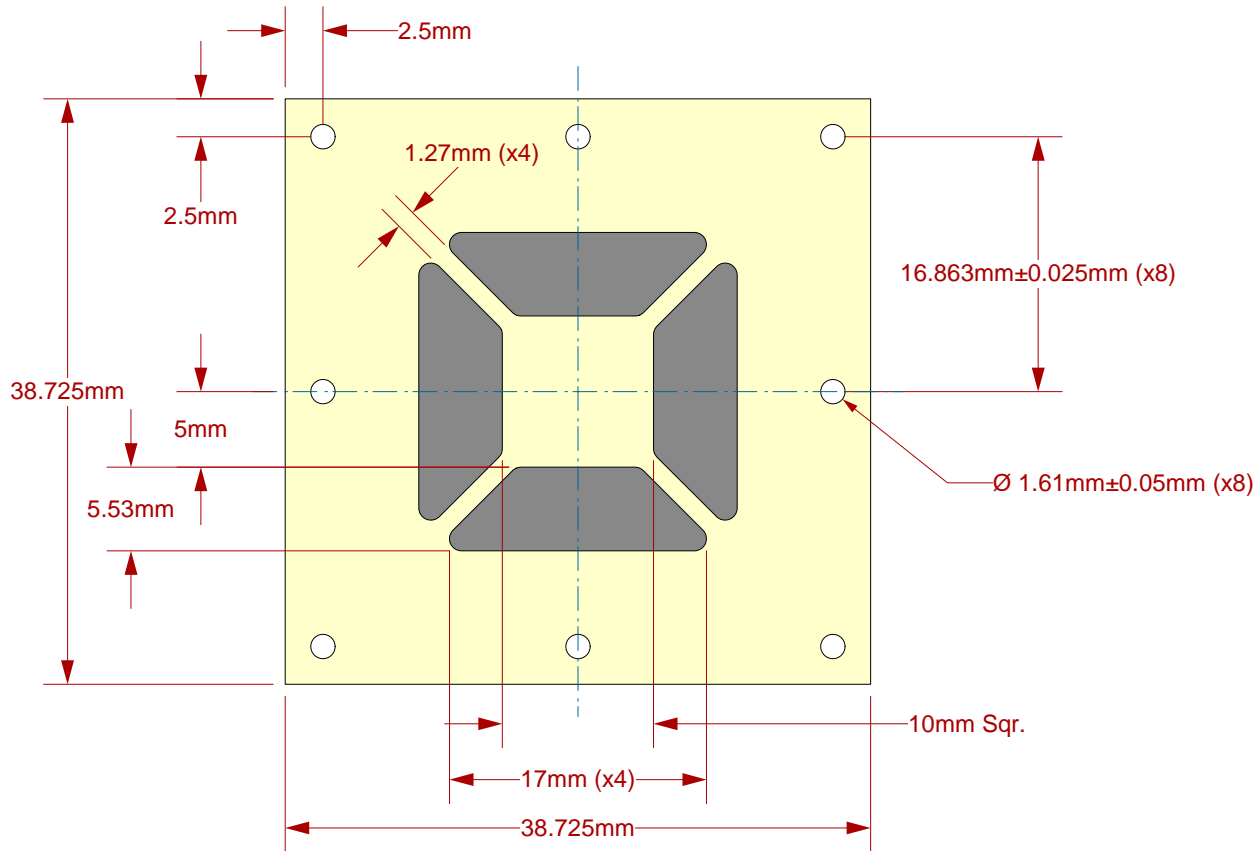
1. Dimensions are in millimeters.
 2. Interpret dimensions and tolerances per ASME Y14.5M-1994.
- Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.
 - Datum Z (seating plane) is defined by the spherical crowns of the solder balls.
 - Parallelism measurement shall exclude any effect of mark on top surface of package.

DIM	MIN	MAX
A		3.5
A1	0.4	0.6
b		0.7
D	31.00 BSC	
E	31.00 BSC	
e	1.0 BSC	

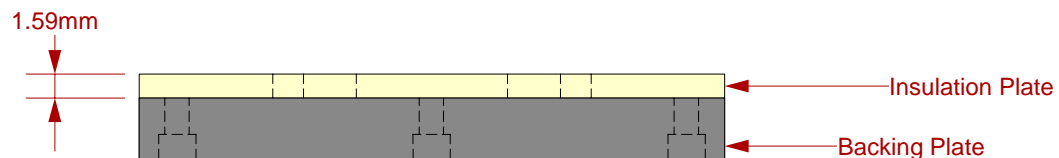
Array 30x30

	CG-BGA-4001 Drawing	Status: Released	Scale: -	Rev: A
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		File: CG-BGA-4001 Dwg.mcd	Modified:	


Top View

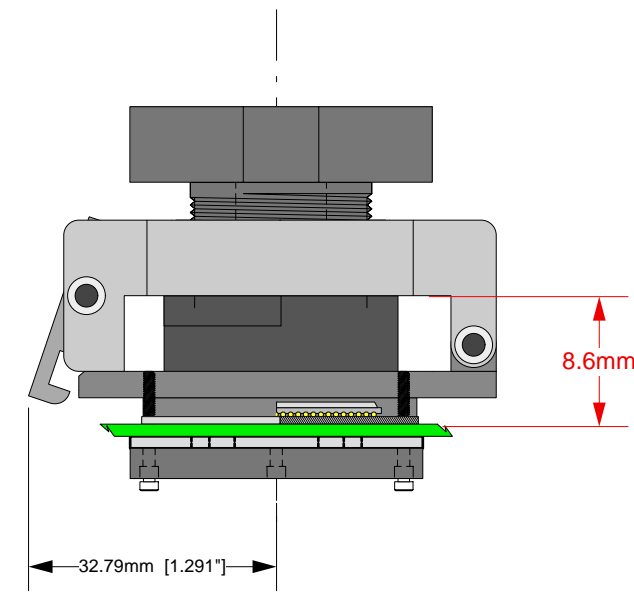
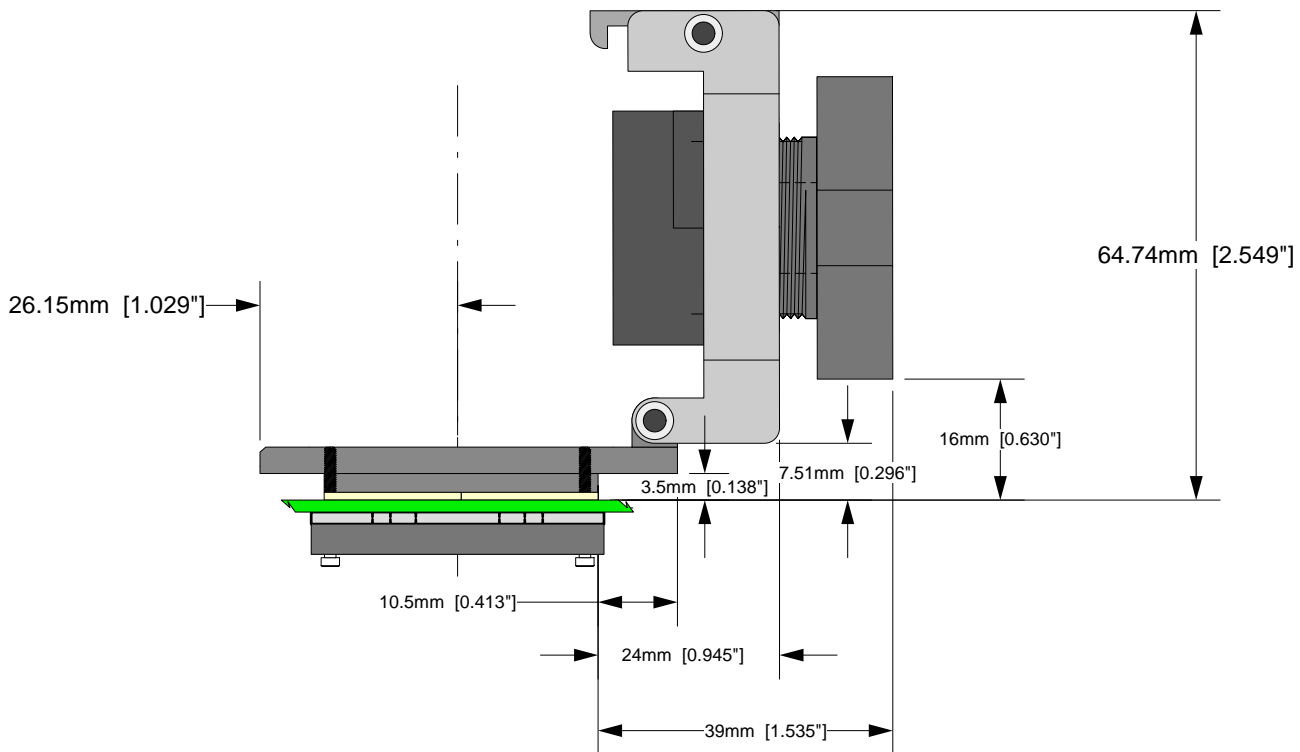
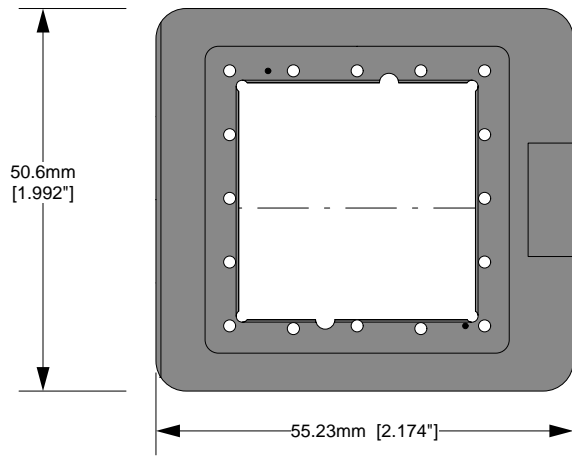



Side View



Description: Insulation Plate and Backing Plate

	CG-BGA-4001 Drawing	Status: Released	Scale: -	Rev: A
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		File: CG-BGA-4001 Dwg.mcd	Modified:	



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	<p>Drawing: J. Glab</p>	<p>Date: 7/30/07</p>		<p>Modified:</p>
	<p>File: CG-BGA-4001 Dwg.mcd</p>			